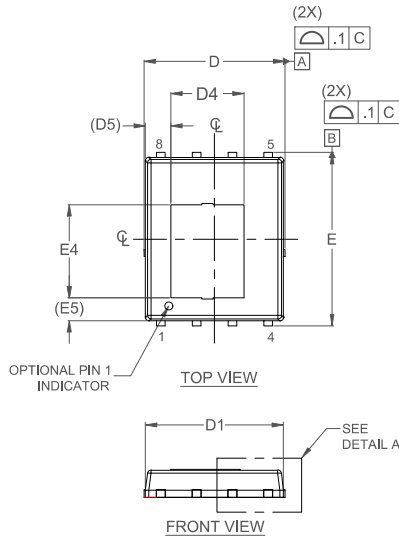
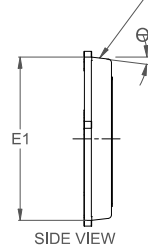


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DATE 06 JUL 2021

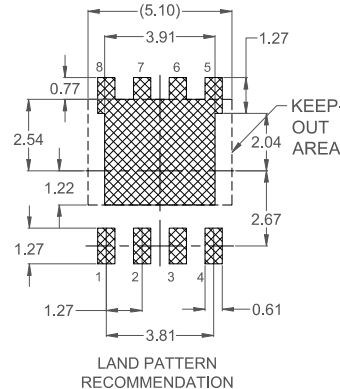
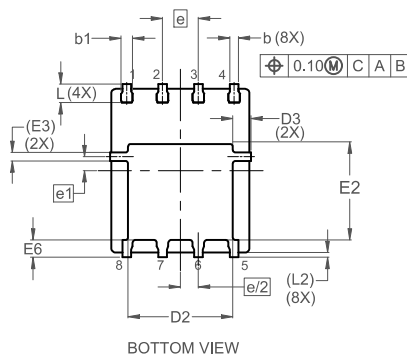
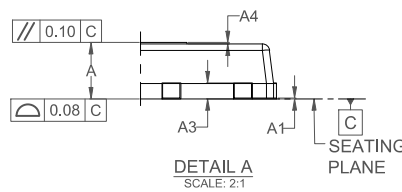


OPTIONAL DRAFT ANGLE
MAY APPEAR ON FOUR
SIDES OF THE PACKAGE



NOTES:

- △A) PACKAGE IS NOT FULLY COMPLIANT TO JEDEC MO-240, VARIATION AA.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	—	0.05
A3	0.23	0.28	0.33
A4	0.00	—	0.05
b	0.31	0.36	0.41
b1	0.36	0.41	0.46
D	4.90	5.00	5.10
D1	4.80	4.90	5.00
D2	3.62	3.72	3.82
D3	0.54	0.64	0.74
D4	2.60	2.70	2.80
D5	0.90 REF		
E	6.05	6.15	6.25
E1	5.70	5.80	5.90
E2	3.31	3.41	3.51
E3	0.25	0.30	0.35
E4	3.30	3.40	3.50
E5	0.81 REF		
E6	0.51	0.61	0.71
e	1.27 BSC		
e/2	0.635 BSC		
e1	0.49 BSC		
L	0.56	0.66	0.76
L2	0.175 REF		
Θ	0°	—	12°

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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